2SC2188

Silicon NPN epitaxial planar type

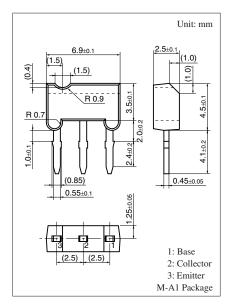
For intermediate frequency amplification of TV image

■ Features

- High transition frequency f_T
- Satisfactory linearity of forward current transfer ratio h_{FE}
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board

■ Absolute Maximum Ratings $T_a = 25$ °C

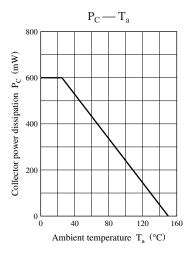
Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	45	V	
Collector-emitter voltage (Base open)	V _{CEO}	35	V	
Emitter-base voltage (Collector open)	V_{EBO}	4	V	
Collector current	I_C	50	mA	
Collector power dissipation	P _C	600	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

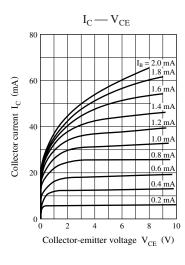


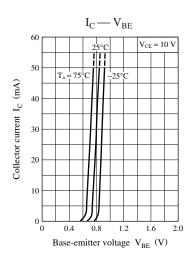
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

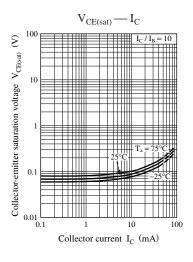
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \ \mu A, I_E = 0$	45			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	35			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \ \mu A, I_C = 0$	4			V
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 20 \text{ V}, I_{B} = 0$			10	μΑ
Forward current transfer ratio	h_{FE}	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}$	20	50	100	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 20 \text{ mA}, I_B = 2 \text{ mA}$			0.5	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 100 \text{ MHz}$	300	500		MHz
Reverse transfer capacitance	C _{re}	$V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 10.7 \text{ MHz}$			1.5	pF
(Common emitter)						
Power gain	G_{P}	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 58 \text{ MHz}$		18		dB

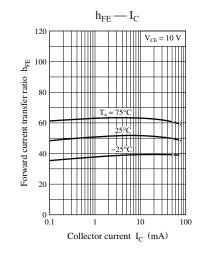
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

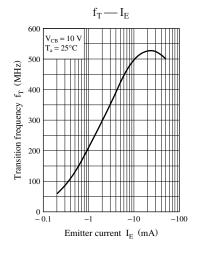


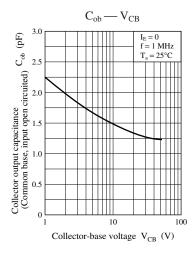


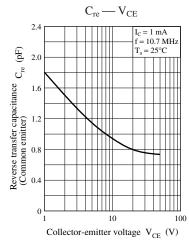


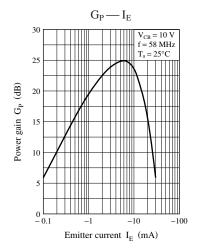












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